



# BCP55T series

60 V, 1 A NPN medium power transistors

Rev. 1 — 29 April 2019

Product data sheet

## 1. Product profile

### 1.1. General description

NPN medium power transistors in a medium power SOT223 (SC73) Surface-Mounted Device (SMD) plastic package.

Table 1. Product overview

| Type number | Package  |       | NPN complement |
|-------------|----------|-------|----------------|
|             | Nexperia | JEDEC |                |
| BCP55T      | SOT223   | SC-73 | BCP52T         |
| BCP55-10T   |          |       | BCP52-10T      |
| BCP55-16T   |          |       | BCP52-16T      |

### 1.2. Features and benefits

- High collector current capability  $I_C$  and  $I_{CM}$
- Three current gain selections
- High power dissipation capability
- AEC-Q101 qualified

### 1.3. Applications

- Linear voltage regulators
- MOSFET drivers
- High-side switches
- Power management
- Amplifiers

### 1.4. Quick reference data

Table 2. Quick reference data

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

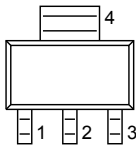
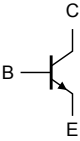
| Symbol    | Parameter                 | Conditions                           | Min | Typ | Max | Unit |
|-----------|---------------------------|--------------------------------------|-----|-----|-----|------|
| $V_{CEO}$ | collector-emitter voltage | open base                            | -   | -   | 60  | V    |
| $I_C$     | collector current         |                                      | -   | -   | 1   | A    |
| $I_{CM}$  | peak collector current    | single pulse; $t_p \leq 1\text{ ms}$ | -   | -   | 2   | A    |

| Symbol    | Parameter       | Conditions                                   |     | Min | Typ | Max | Unit |
|-----------|-----------------|--|-----|-----|-----|-----|------|
| $h_{FE}$  | DC current gain |  |     |     |     |     |      |
|           | BCP55T          | $V_{CE} = 2 \text{ V}; I_C = 150 \text{ mA}$ | [1] | 63  | -   | 250 |      |
|           | BCP55-10T       |  | [1] | 63  | -   | 160 |      |
| BCP55-16T | [1]             |  | 100 | -   | 250 |     |      |

[1] pulsed;  $t_p \leq 300 \mu\text{s}$ ;  $\delta \leq 0.02$

## 2. Pinning information

Table 3. Pinning

| Pin | Symbol | Description | Simplified outline   | Graphic symbol  |
|-----|--------|-------------|--|---|
| 1   | B      | base        |  | <br>sym123 |
| 2   | C      | collector   |  |   |
| 3   | E      | emitter     |  |   |
| 4   | C      | collector   |  |   |

## 3. Ordering information

Table 4. Ordering information

| Type number | Package |  | Version |
|-------------|---------|--|---------|
|             | Name    | Description  |         |
| BCP55T      | SC-73   | plastic, surface-mounted package with increased heatsink;<br>4 leads | SOT223  |
| BCP55-10T   |         |  |         |
| BCP55-16T   |         |  |         |

## 4. Marking

Table 5. Marking

| Type number | Marking code |
|-------------|--------------|
| BCP55T      | BCP55T       |
| BCP55-10T   | P5510T       |
| BCP55-16T   | P5516T       |

## 5. Limiting values

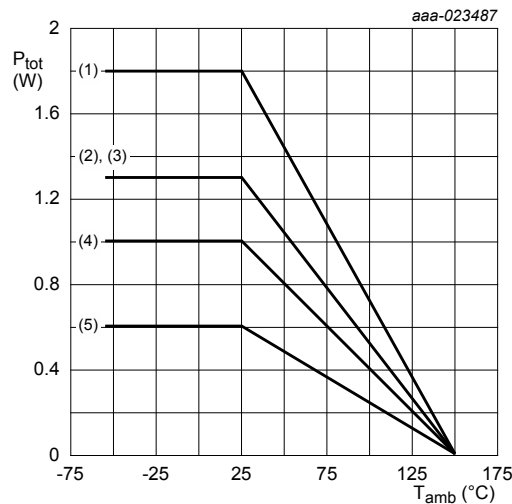
**Table 6. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

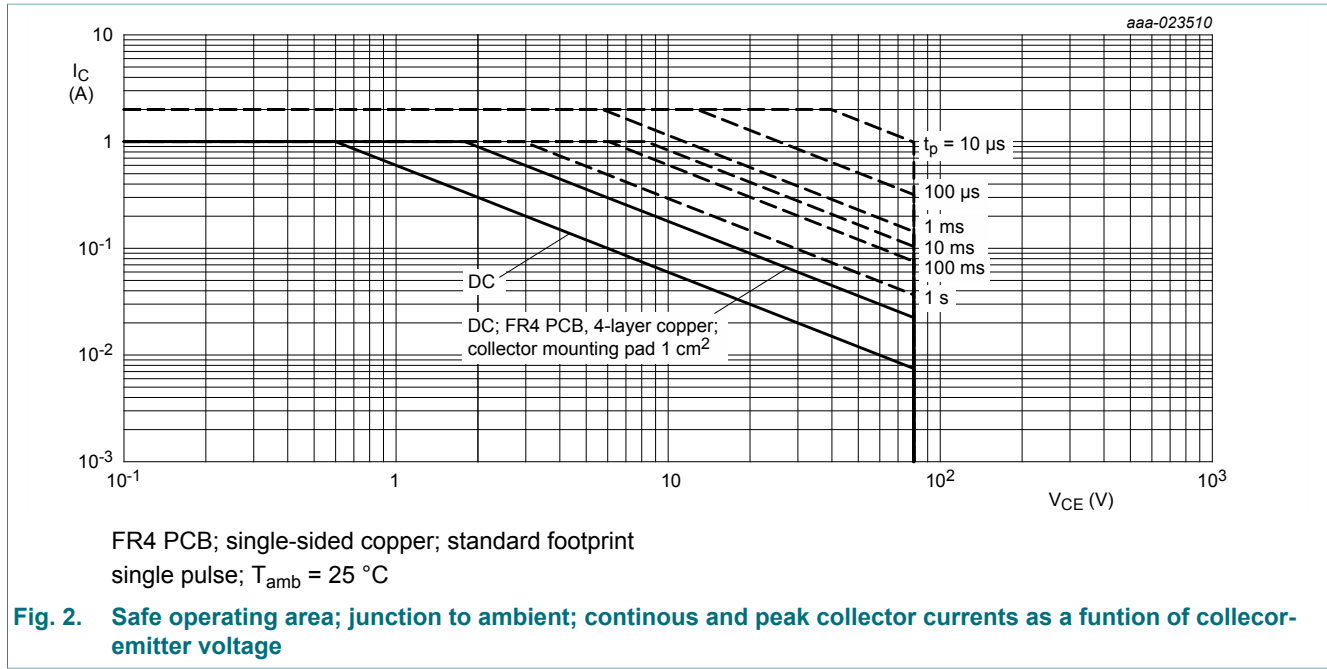
| Symbol    | Parameter                 | Conditions                           | Min | Max | Unit |
|-----------|---------------------------|--------------------------------------|-----|-----|------|
| $V_{CBO}$ | collector-base voltage    | open emitter                         | -   | 60  | V    |
| $V_{CEO}$ | collector-emitter voltage | open base                            | -   | 60  | V    |
| $V_{EBO}$ | emitter-base voltage      | open collector                       | -   | 5   | V    |
| $I_C$     | collector current         |                                      | -   | 1   | A    |
| $I_{CM}$  | peak collector current    | single pulse; $t_p \leq 1\text{ ms}$ | -   | 2   | A    |
| $I_B$     | base current              |                                      | -   | 0.2 | A    |
| $I_{BM}$  | peak base current         | single pulse; $t_p \leq 1\text{ ms}$ | -   | 0.3 | A    |
| $P_{tot}$ | total power dissipation   | $T_{amb} \leq 25\text{ °C}$          | [1] | 0.6 | W    |
|           |                           |                                      | [2] | 1   | W    |
|           |                           |                                      | [3] | 1.3 | W    |
|           |                           |                                      | [4] | 1.3 | W    |
|           |                           |                                      | [5] | 1.8 | W    |
| $T_j$     | junction temperature      |                                      | -   | 150 | °C   |
| $T_{amb}$ | ambient temperature       |                                      | -55 | 150 | °C   |
| $T_{stg}$ | storage temperature       |                                      | -65 | 150 | °C   |

- [1] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated and standard footprint.
- [2] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated; mounting pad for collector 1 cm<sup>2</sup>.
- [3] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated; mounting pad for collector 6 cm<sup>2</sup>.
- [4] Device mounted on an FR4 Printed-Circuit-Board (PCB); 4-layer copper; tin-plated and standard footprint.
- [5] Device mounted on an FR4 Printed-Circuit-Board (PCB); 4-layer copper; tin-plated; mounting pad for collector 1 cm<sup>2</sup>.



- (1) FR4 PCB; 4-layer copper; 1 cm<sup>2</sup>
- (2) FR4 PCB; single-sided copper; 6 cm<sup>2</sup>
- (3) FR4 PCB; 4-layer copper; standard footprint
- (4) FR4 PCB; single-sided copper; 1 cm<sup>2</sup>
- (5) FR4 PCB; single-sided copper; standard footprint

**Fig. 1. Power derating curves**



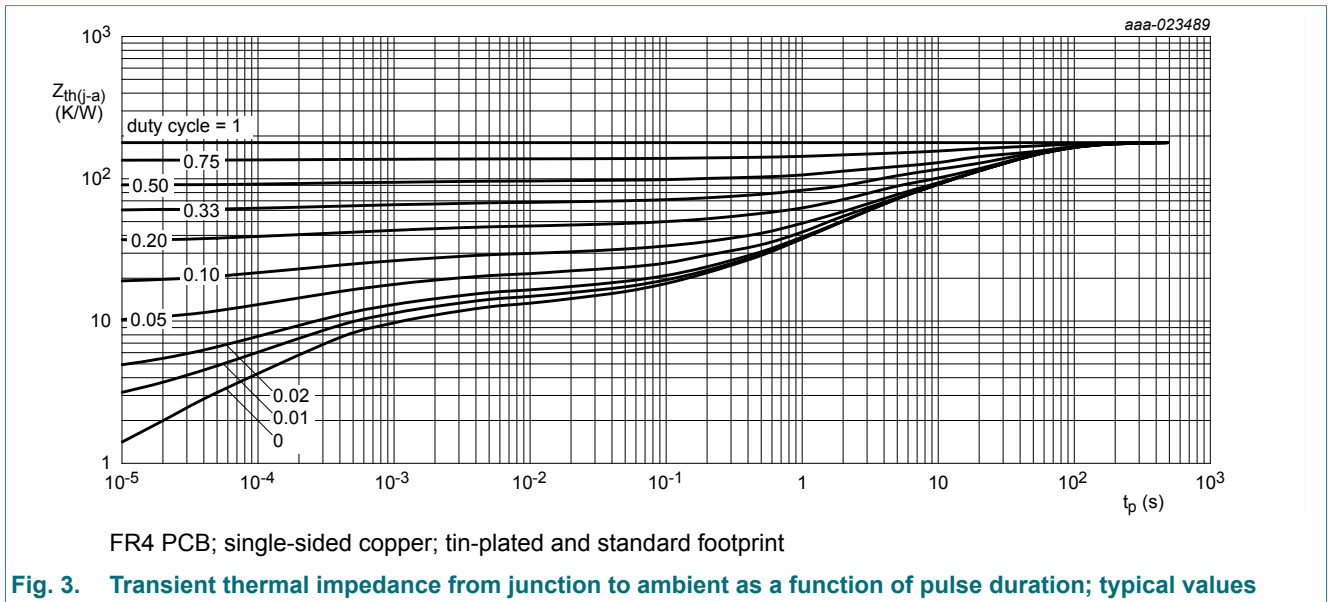
## 6. Thermal characteristics

**Table 7. Thermal characteristics**

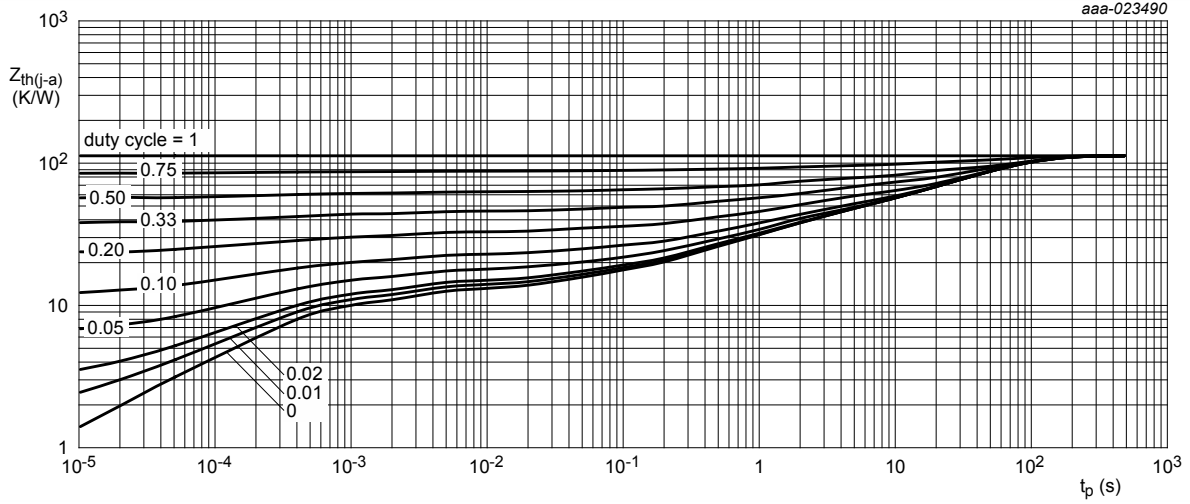
$T_{amb} = 25\text{ °C}$  unless otherwise specified.

| Symbol        | Parameter  | Conditions  |     | Min | Typ | Max | Unit |
|---------------|--|-------------|-----|-----|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient      | in free air | [1] | -   | -   | 209 | K/W  |
|               |  |             | [2] |     |     | 125 | K/W  |
|               |  |             | [3] |     |     | 97  | K/W  |
|               |  |             | [4] | -   | -   | 97  | K/W  |
|               |  |             | [5] | -   | -   | 70  | K/W  |
| $R_{(j-sp)}$  | thermal resistance from junction to solder point |             |     | -   | -   | 18  | K/W  |

- [1] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated and standard footprint.
- [2] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated; mounting pad for collector 1 cm<sup>2</sup>.
- [3] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated; mounting pad for collector 6 cm<sup>2</sup>.
- [4] Device mounted on an FR4 Printed-Circuit-Board (PCB); 4-layer copper; tin-plated and standard footprint.
- [5] Device mounted on an FR4 Printed-Circuit-Board (PCB); 4-layer copper; tin-plated; mounting pad for collector 1 cm<sup>2</sup>.

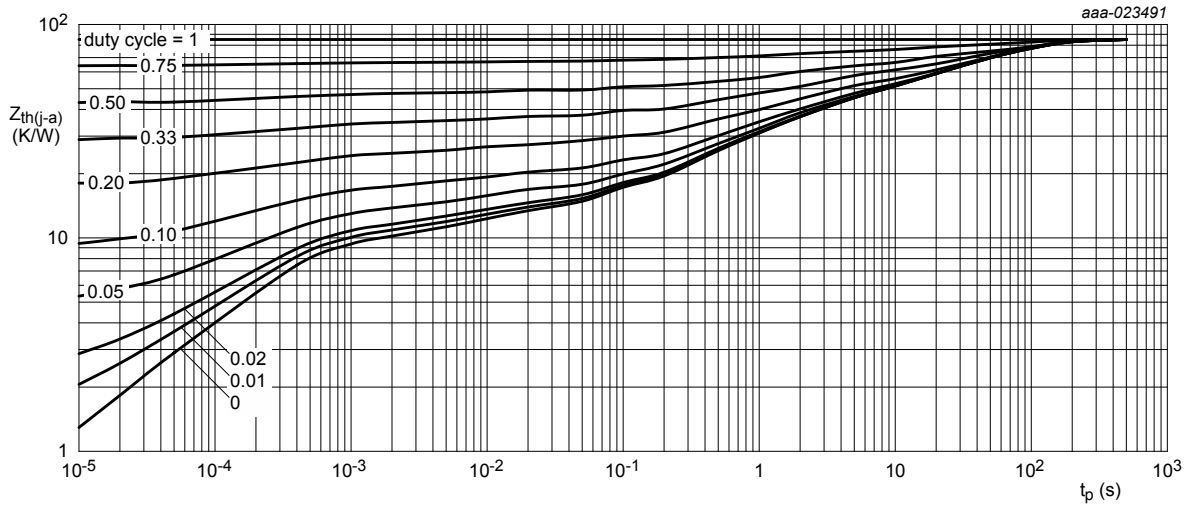


**Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



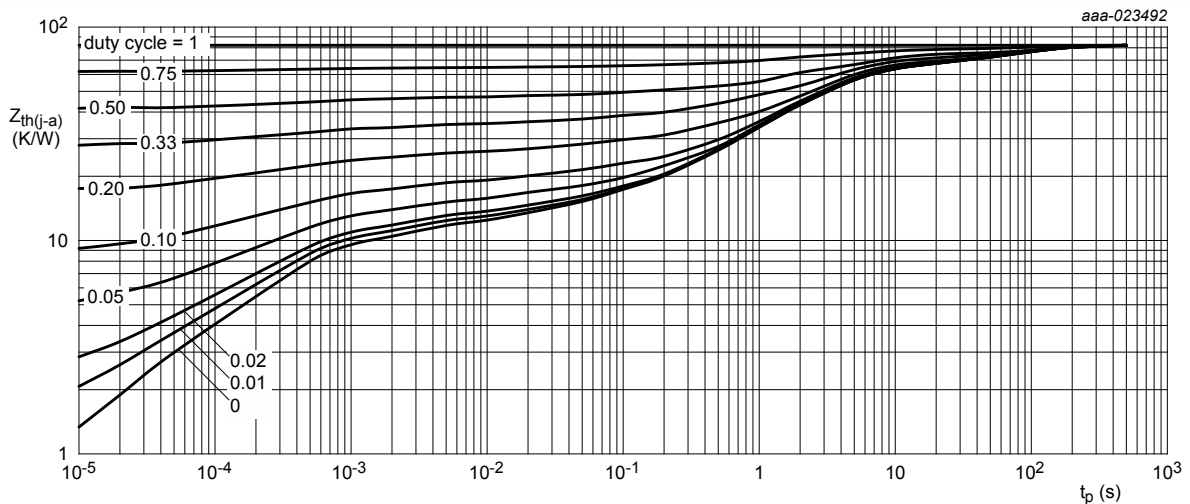
FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 1 cm<sup>2</sup>

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



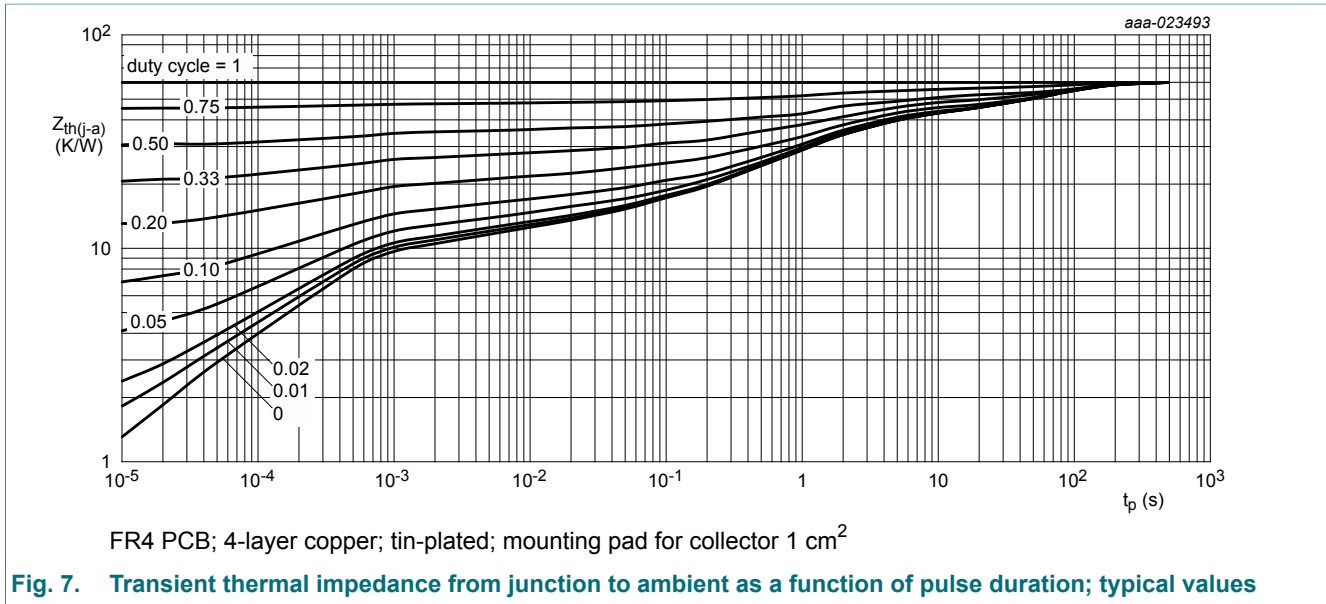
FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 6 cm<sup>2</sup>

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB; 4-layer copper; tin-plated and standard footprint

Fig. 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



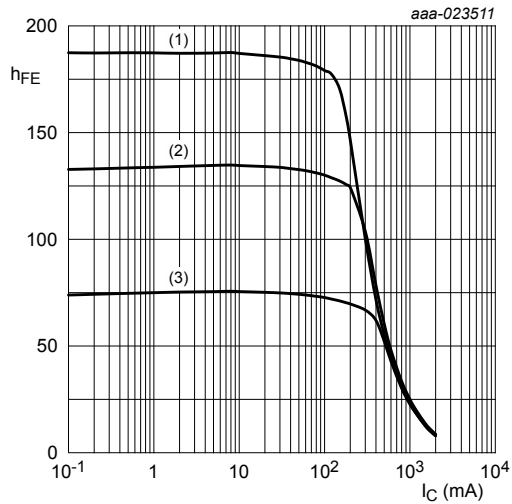
## 7. Characteristics

**Table 8. Characteristics**

*T<sub>amb</sub> = 25 °C unless otherwise specified.*

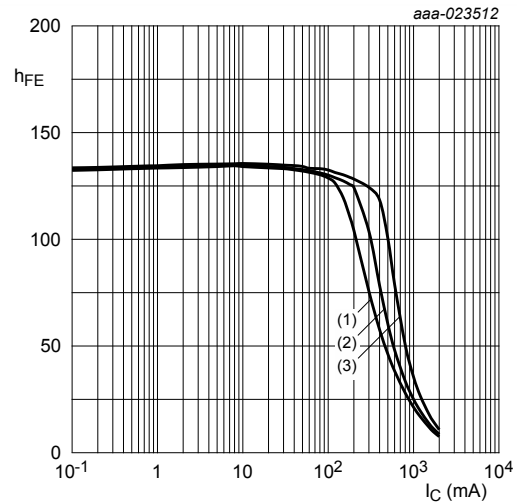
| Symbol               | Parameter                            | Conditions   | Min     | Typ | Max | Unit |
|----------------------|--------------------------------------|--|---------|-----|-----|------|
| V <sub>(BR)CBO</sub> | collector-base breakdown voltage     | I <sub>C</sub> = 100 μA; I <sub>E</sub> = 0 A                            | 60      | -   | -   | V    |
| V <sub>(BR)CEO</sub> | collector-emitter breakdown voltage  | I <sub>C</sub> = 2 mA; I <sub>E</sub> = 0 A                              | 60      | -   | -   | V    |
| V <sub>(BR)EBO</sub> | emitter-base breakdown voltage       | I <sub>E</sub> = 100 μA; I <sub>C</sub> = 0 A                            | 5       | -   | -   | V    |
| I <sub>CBO</sub>     | collector-base cut-off current       | V <sub>CB</sub> = 30 V; I <sub>E</sub> = 0 A                             | -       | -   | 100 | nA   |
|                      |                                      | V <sub>CB</sub> = 30 V; I <sub>E</sub> = 0 A; T <sub>J</sub> = 150 °C    | -       | -   | 10  | μA   |
| I <sub>EBO</sub>     | emitter-base cut-off current         | V <sub>EB</sub> = 5 V; I <sub>C</sub> = 0 A                              | -       | -   | 100 | nA   |
| h <sub>FE</sub>      | DC current gain                      |  |         |     |     |      |
|                      | BCP55T, -10T, -16T                   | V <sub>CE</sub> = 2 V; I <sub>C</sub> = 5 mA                             | 63      | -   | -   |      |
|                      |                                      | V <sub>CE</sub> = 2 V; I <sub>C</sub> = 500 mA                           | [1] 40  | -   | -   |      |
|                      | BCP55T                               | V <sub>CE</sub> = 2 V; I <sub>C</sub> = 150 mA                           | [1] 63  | -   | 250 |      |
|                      | BCP55-10T                            | V <sub>CE</sub> = 2 V; I <sub>C</sub> = 150 mA                           | [1] 63  | -   | 160 |      |
|                      | BCP55-16T                            | V <sub>CE</sub> = 2 V; I <sub>C</sub> = 150 mA                           | [1] 100 | -   | 250 |      |
| V <sub>CEsat</sub>   | collector-emitter saturation voltage | I <sub>C</sub> = 500 mA; I <sub>B</sub> = 50 mA                          | [1] -   | -   | 500 | mV   |
| V <sub>BE</sub>      | base-emitter voltage                 | V <sub>CE</sub> = 2 V; I <sub>C</sub> = 500 mA                           | [1] -   | -   | 1   | V    |
| f <sub>T</sub>       | transition frequency                 | V <sub>CE</sub> = 5 V; I <sub>C</sub> = 50 mA; f = 100 MHz               | 100     | 155 | -   | MHz  |
| C <sub>c</sub>       | collector capacitance                | V <sub>CB</sub> = 10 V; I <sub>E</sub> = i <sub>e</sub> = 0 A; f = 1 MHz | -       | 4.5 | -   | pF   |

[1] pulsed; t<sub>p</sub> ≤ 300 μs; δ ≤ 0.02



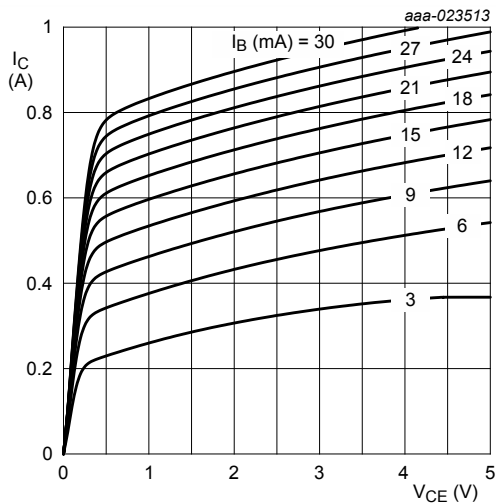
$V_{CE} = 2\text{ V}$   
 (1)  $T_{amb} = 100\text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25\text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -55\text{ }^\circ\text{C}$

Fig. 8. DC current gain as a function of collector current; typical values



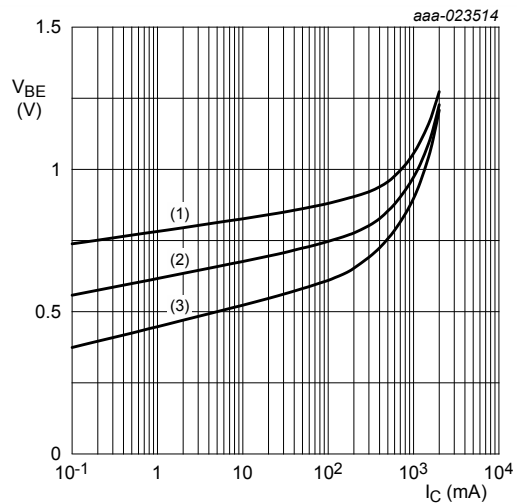
$T_{amb} = 25\text{ }^\circ\text{C}$   
 (1)  $V_{CE} = 1\text{ V}$   
 (2)  $V_{CE} = 2\text{ V}$   
 (3)  $V_{CE} = 5\text{ V}$

Fig. 9. DC current gain as a function of collector current; typical values



$T_{amb} = 25\text{ }^\circ\text{C}$

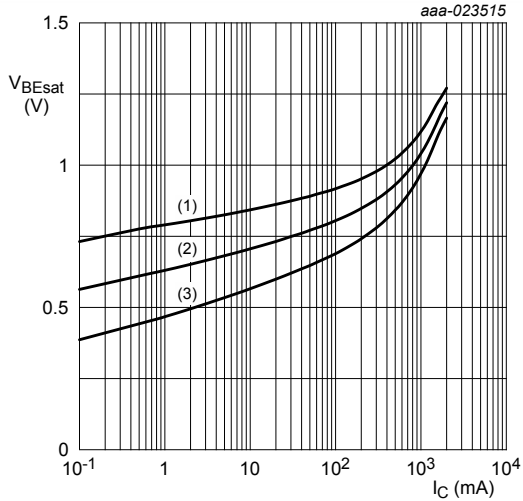
Fig. 10. Collector current as a function of collector-emitter voltage; typical values



$V_{CE} = 2\text{ V}$   
 (1)  $T_{amb} = -55\text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25\text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100\text{ }^\circ\text{C}$

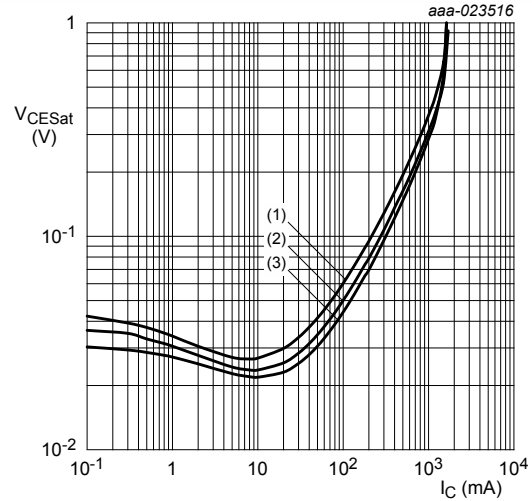
Fig. 11. Base-emitter voltage as a function of collector current; typical values





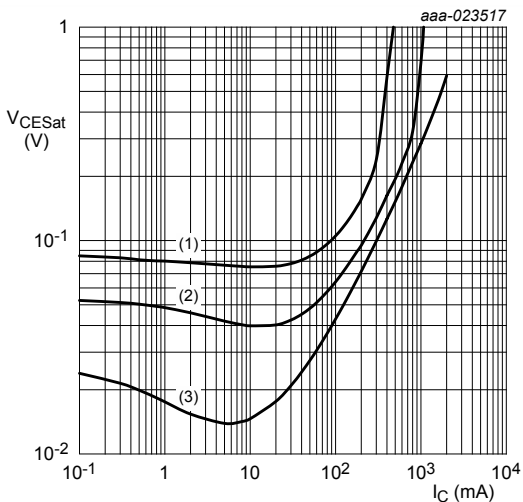
$I_C/I_B = 10$   
 (1)  $T_{amb} = -55\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 100\text{ °C}$

Fig. 12. Base-emitter saturation voltage as a function of collector current; typical values



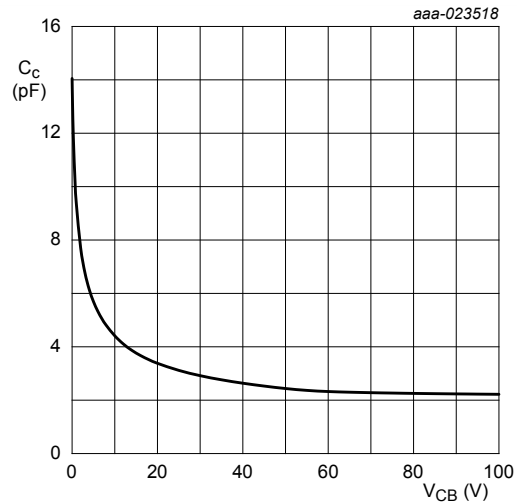
$I_C/I_B = 10$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -55\text{ °C}$

Fig. 13. Collector-emitter saturation voltage as a function of collector current; typical values



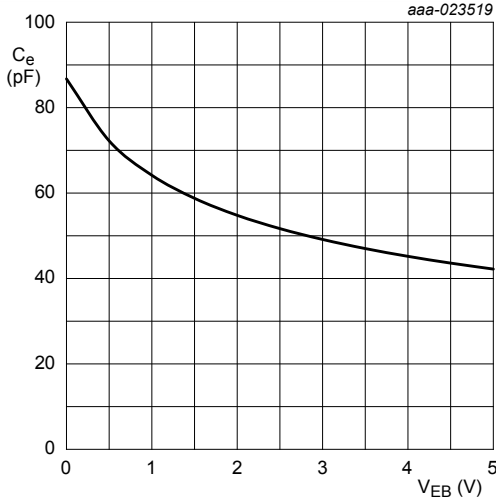
$T_{amb} = 25\text{ °C}$   
 (1)  $I_C/I_B = 50$   
 (2)  $I_C/I_B = 20$   
 (3)  $I_C/I_B = 5$

Fig. 14. Collector-emitter saturation voltage as a function of collector current; typical values



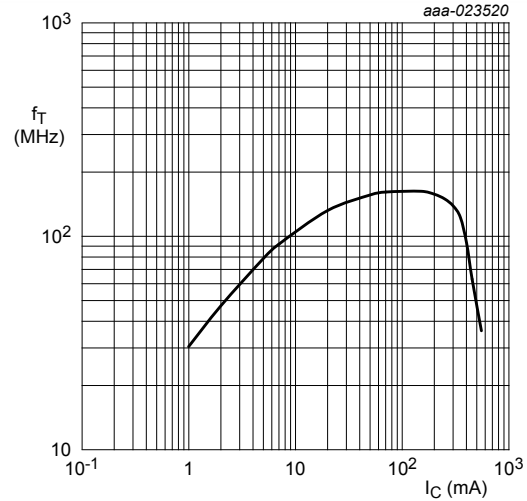
$f = 1\text{ MHz}; T_{amb} = 25\text{ °C}$

Fig. 15. Collector capacitance as a function of collector-base voltage; typical values



$f = 1 \text{ MHz}; T_{amb} = 25 \text{ }^\circ\text{C}$

Fig. 16. Emitter capacitance as a function of emitter-base voltage; typical values



$V_{CE} = 5 \text{ V}$

$f = 100 \text{ MHz}; T_{amb} = 25 \text{ }^\circ\text{C}$

Fig. 17. Transition frequency as a function of collector current; typical values

## 8. Test information

### 8.1. Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

## 9. Package outline

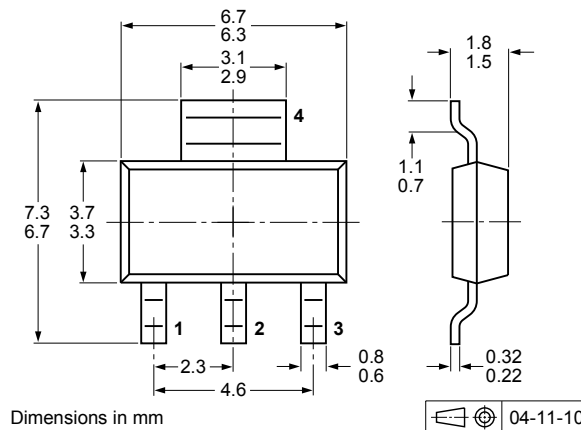
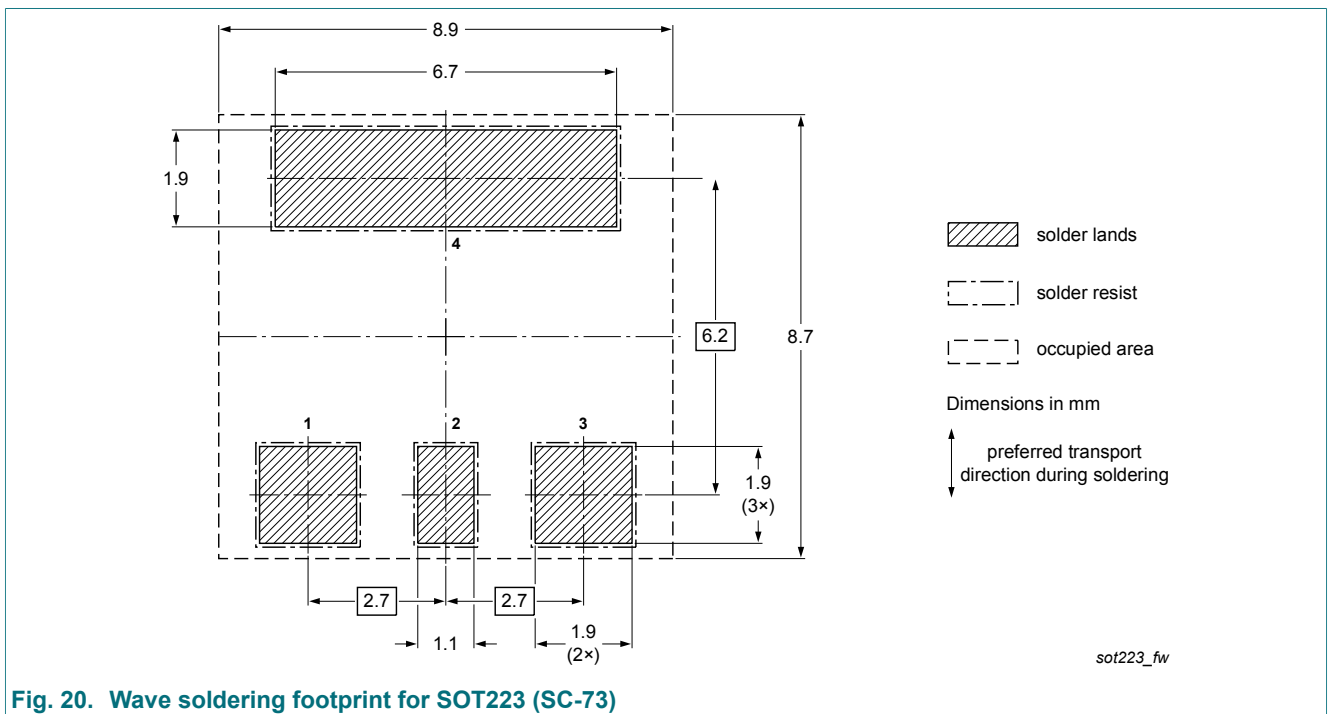
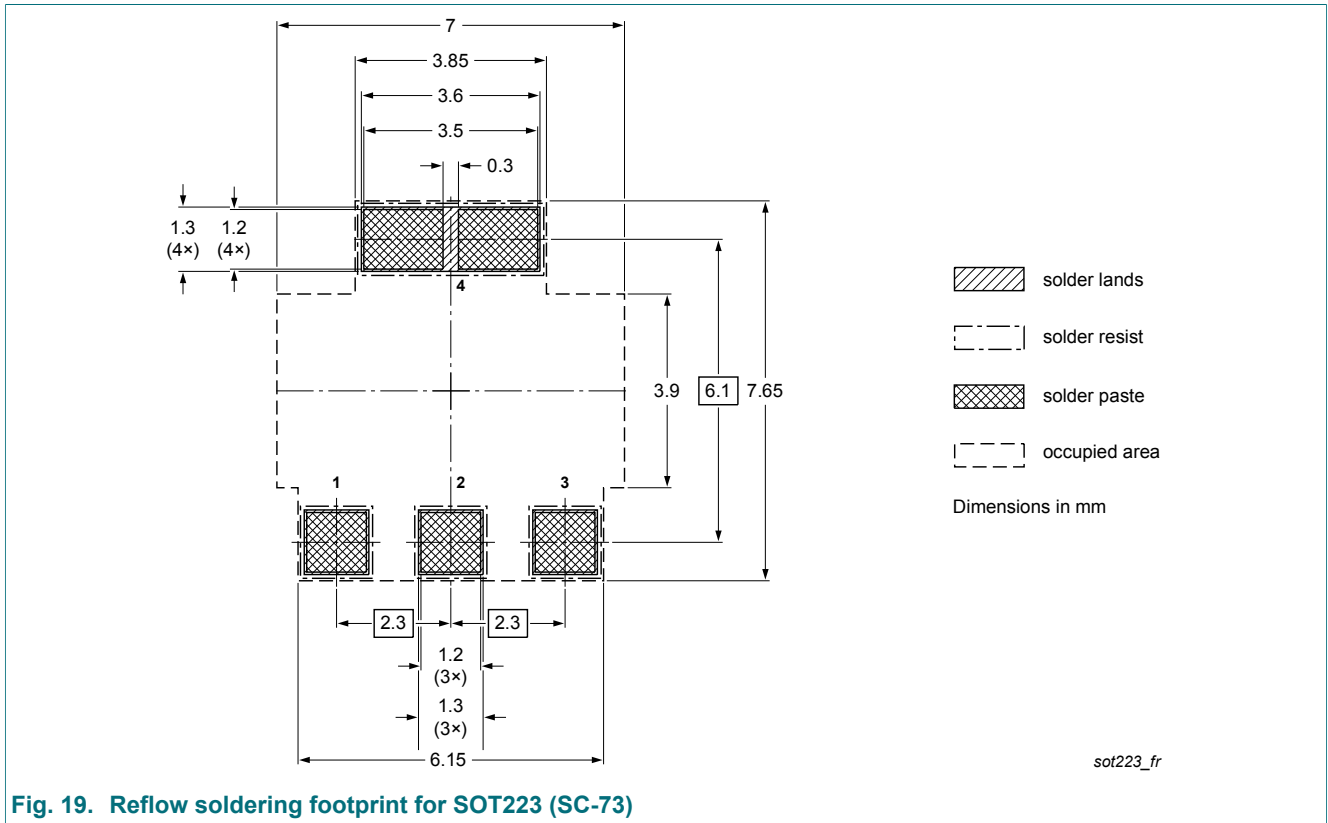


Fig. 18. Package outline SOT223 (SC-73)

10. Soldering



## 11. Revision history

Table 9. Revision history

| Document ID    | Release date | Data sheet status  | Change notice | Supersedes |
|----------------|--------------|--------------------|---------------|------------|
| BCP55T_SER v.1 | 20190429     | Product data sheet | -             | -          |

## 12. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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